



Material Content Data Sheet



Sales Product Name		IPZ40N04S5-5R4		Issued		1. August 2018		
MA#		MA001338268						
Package		PG-TSDSON-8-32		Weight*		35.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.336	0.95	0.95	9491	9491
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		88	
	non noble metal	zinc	7440-66-6	0.012	0.04		352	
	non noble metal	iron	7439-89-6	0.249	0.70		7038	
wire	non noble metal	copper	7440-50-8	10.102	28.58	29.33	285758	293236
	noble metal	gold	7440-57-5	0.030	0.09	0.09	861	861
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1054
encapsulation	plastics	epoxy resin	-	1.918	5.43		54255	
	inorganic material	silicondioxide	60676-86-0	16.667	47.12	52.66	471442	526751
	leadfinish	non noble metal	tin	7440-31-5	0.400	1.13	1.13	11322
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2422	2422
solder	non noble metal	tin	7440-31-5	0.010	0.03		294	
	noble metal	silver	7440-22-4	0.013	0.04		367	
	non noble metal	lead	7439-92-1	0.496	1.40	1.47	14035	14696
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		17	
	non noble metal	zinc	7440-66-6	0.002	0.01		66	
	non noble metal	iron	7439-89-6	0.047	0.13		1329	
heat sink CLIP	non noble metal	copper	7440-50-8	1.908	5.40	5.54	53960	55372
	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
heat sink CLIP	non noble metal	iron	7439-89-6	0.073	0.21		2060	
	non noble metal	copper	7440-50-8	2.958	8.37	8.59	83660	85849
	*deviation	< 10%				Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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